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Carbon Nanotubes for Interconnects

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Message from the Guest Editors

Dear Colleagues,

Future nanoelectronics technology will be enabled by the effective possibility of complementing the nanoscale devices to the boards, and a major concern is given by the performance of interconnections in nanopackages.

Due to their outstanding physical properties, carbon-based materials are promising candidates for nanointerconnections: In particular, carbon nanotubes have sparked a great deal of interest because of their desirable properties, such as large electron mean free path, mechanical strength, high thermal conductivity, and large current carrying capacity.

This Special Issue is aiming at providing the state-of-the-art on carbon-based interconnections, presenting the most relevant results in modelling, fabrication, and integration, and providing examples of the most recent applications for on-/off-chip interconnections.

Prof. Dr. Antonio Maffucci Prof. Dr. Aida Todri-Sanial *Guest Editors*









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Editor-in-Chief

Message from the Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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